

General statement on RoHS/China RoHS

Date: July 2020

Dear Customers,

The following statement applies to all unassembled printed circuit boards produced by the KSG Group. In accordance with EU Directive 2011/65/EU and amendments 2015/863/EU and 2017/2102/EU, the following restricted materials are not used in our products above the compulsory weight limit:

- Mercury (0.1%)
- Lead (0.1%)
- Cadmium (0.01 %)
- Hexavalent chromium (0.1%)
- Polybrominated biphenyls (PBB) (0.1%)
- Polybrominated diphenyl ethers (PBDE) (e.g. pentaBDE and octaBDE) (0.1 %)
- Phthalates DEHP, BBP, DBP, DIBP (0.1%)

A restriction applies to the use of lead where printed circuit boards are explicitly ordered with a leaded HAL (hot air levelling) solder surface. The end product only conforms to EU Directive 2011/65/EU if you have a valid exemption for the end product. Of course, we have RoHS-compliant solder surfaces available in-house as an alternative.

The halogenated flame retardant tetrabromobisphenol-A (TBBP-A) used in the base material is not a prohibited substance, especially as it no longer occurs in its original form in the printed circuit board (cured epoxy resin matrix), but has (reactively) formed a new compound.

This statement also applies in respect of China-RoHS 2 and Directive 2012/19/EU (WEEE).

KSG regularly monitors the above directives for updates and amends its declarations as necessary.

Please do not hesitate to contact us if you have any further questions.

KSG Group

In representation of Holger Bönitz
Head of Central Quality Management

On behalf of Gunter Laubert
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